PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DONGJIN KIM	06/04/2020
CHANGHAK CHOI	06/04/2020
BONSEOK KOO	06/04/2020
CHANGSU JANG	06/04/2020
MOONSEONG JEONG	06/04/2020
EUNYONG JANG	06/04/2020
BYUNG KUN KIM	06/04/2020

RECEIVING PARTY DATA

Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.
Street Address:	MAEYOUNG-RO 150 (MAETAN-DONG), YOUNGTONG-GU
City:	SUWON-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16896468

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 2027395000

Email: patents@morganlewis.com, Sandra.Johnson@morganlewis.com

Correspondent Name: MORGAN, LEWIS & BOCKIUS LLP Address Line 1: 1111 PENNSYLVANIA AVENUE NW

Address Line 4: WASHINGTON, D.C. 20004

ATTORNEY DOCKET NUMBER:	123193-7995-US
NAME OF SUBMITTER:	SANDRA JOHNSON
SIGNATURE:	/Sandra Johnson/
DATE SIGNED:	06/10/2020

Total Attachments: 3

PATENT REEL: 052891 FRAME: 0102

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> PATENT REEL: 052891 FRAME: 0103

COMBINED DECLARATION (37 CFR 1.63) FOR U.S. PATENT APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT OF INVENTION

Title of Invention	-	TILAYER CERAMIC ELECTRONIC COMPONENT AND HOD OF MANUFACTURING THE SAME
DECLARATION As the below named	and und	iersigned inventor, I hereby declare that:
This declaration is directed to:		The attached application, or United States application or PCT international application number filed on

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

Note to Inventor: 37 C.F.R. § 1.63(c) states: A person may not execute an oath or declaration for an application unless that person has reviewed and understands the contents of the application, including the claims, and is aware of the duty to disclose to the Office all information known to the person to be material to patentability as defined in § 1.56.

ASSIGNMENT

WHEREAS, I have made an invention described and/or claimed in the above-identified application; and

WHEREAS, <u>SAMSUNG ELECTRO-MECHANICS CO., LTD.</u>, a corporation of the Republic of Korea, having a place of business at <u>Maeyoung-ro 150 (Maetan-dong)</u>, <u>Youngtong-gu</u>, <u>Suwon-si</u>, <u>Gveonggi-do</u>, <u>Republic of Korea</u>, (hereinafter referred to as "ASSIGNEE") desires to acquire the entire right, title, and interest in and to said invention in all countries throughout the world and the above-identified United States patent application;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. I have assigned and do hereby assign to the ASSIGNEE, and its lawful successors and assigns, the entire right, title, and interest in and to said invention, the above-identified United States patent application and all divisions, continuations, and continuations-in-part of said application, and reissues, extensions, and renewals of Letters Patent granted thereon, and all corresponding patent applications filed in countries foreign to the United States ("foreign countries") and corresponding international patent applications, and all Letters Patents issuing on any such patent applications in the United States and foreign countries;

I hereby assign to the ASSIGNEE, and its lawful successors and assigns, the right to file patent applications in foreign countries on said invention in its own name and the right to claim priority to the above-identified United States patent application under the terms of the International Convention and any

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other relevant treaties;

I hereby authorize and request the United States Patent and Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE as the assignee of my entire right, title, and interest in and to the same, for the sole use and benefit of the ASSIGNEE, and its lawful successors and assigns, to the full end of the term for which said Letters Patent may be granted;

I hereby grant the attorney of record the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or other authority for recordation of this document:

I hereby covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment; and

Further, I hereby further covenant and agree that I will, without further consideration, communicate with the ASSIGNEE, and its lawful successors and assigns, any facts known to me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said ASSIGNEE, and its lawful successors or assigns, execute all divisional, continuation, continuation-in-part, and reissue applications, make all rightful oaths and generally do everything possible to aid the ASSIGNEE, and its lawful successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the ASSIGNEE, and its lawful successors and assigns.

IN TESTIMONY WHEREOF, I have hereunto set my hands.

NAME OF INVENTOR (Full Legal Name) : Dongjin KIM				
Signature: TU F2 TC	Date:	4th	Jun.	2520
NAME OF INVENTOR (Full Legal Name) : Changhak CHOI				
Signature: 31 25 35	Date:	4+4	June	. 2-0°2-6
NAME OF INVENTOR (Full Legal Name) : Bonseok KOO		-		
Signature: 747	Date:	454	June.	2020
NAME OF INVENTOR (Full Legal Name) : Changsu JANG		-		
Signature: 76 74	Date:	4th	June	2020
NAME OF INVENTOR (Full Legal Name) : Moonseong JEONG		-		
Signature: 10210	Date:	4+h	Jun	2020
NAME OF INVENTOR (Full Legal Name) : Eunyong JANG		-		
Signature: 155	Date:	9 th	Jun	5010

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Assignee Ref. No. 123193-7995

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NAME OF IN	VENTOR (Full Legal Name) <u>: Byung Kun F</u>	KIM
	minim	·····
		Mill. T. Sunsum
Signature:		Date: 4th Sun 2020

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